

#5/17/01
D. Rabin
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: To Be Assigned
Examiner: To Be Assigned

11000 U.S. PTO
09/942962
08/31/01

In re PATENT APPLICATION of

Applicant(s) : Takaaki SASAKI)

Appln. No. : To Be Assigned)

Filed : August 31, 2001)

For : SEMICONDUCTOR PACKAGE FOR)
THREE-DIMENSIONAL MOUNTING,)
FABRICATION METHOD THEREOF,)
AND SEMICONDUCTOR DEVICE)

Atty. Dkt. : TAI 131)

**INFORMATION
DISCLOSURE
STATEMENT**

Commissioner for Patents
Washington, D.C. 20231

Sir:


This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(b)(1).

Attached is a copy of one Japanese patent publication with an English-language abstract from which the relevance of the publication may be gleaned. The publication is listed on the attached Form PTO-1449.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met as to the document submitted. Consideration of the submitted document is respectfully requested.

Respectfully submitted,

August 31, 2001
Date


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